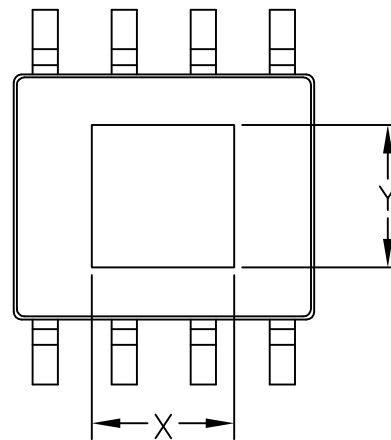


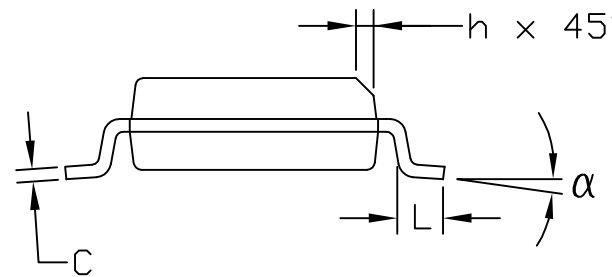
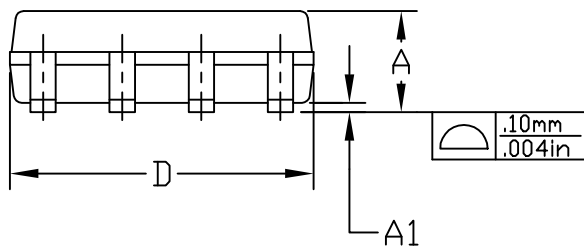
TOP VIEW



BOTTOM VIEW

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.056	0.066	1.43	1.68
A1	0.000	0.004	0.00	0.10
B	0.014	0.019	0.35	0.49
C	0.007	0.010	0.19	0.25
D	0.189	0.196	4.80	4.98
e	0.050	BSC	1.27	BSC
E	0.150	0.157	3.81	3.99
H	0.230	0.244	5.81	6.20
h	0.010	0.016	0.25	0.41
L	0.016	0.035	0.41	0.89
$\alpha$	0°	8°	0°	8°

PKG.	X (mm)		Y (mm)	
	MIN	MAX	MIN	MAX
S8E-12	2.184	2.388	2.184	2.388
S8E-14	2.997	3.200	2.311	2.515



NOTES:

1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .15mm (.006")
3. CONTROLLING DIMENSION: MILLIMETER
4. MEETS JEDEC MS-012 EXCEPT DIMENSION A1.
5. DIMENSIONS X AND Y DEFINE EXPOSED PAD METAL AREA.

**DALLAS SEMICONDUCTOR** **MAXIM**

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE  
8L SOIC, .150" EXPOSED PAD

APPROVAL	DOCUMENT CONTROL NO. 21-0111	REV. C	1/1
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